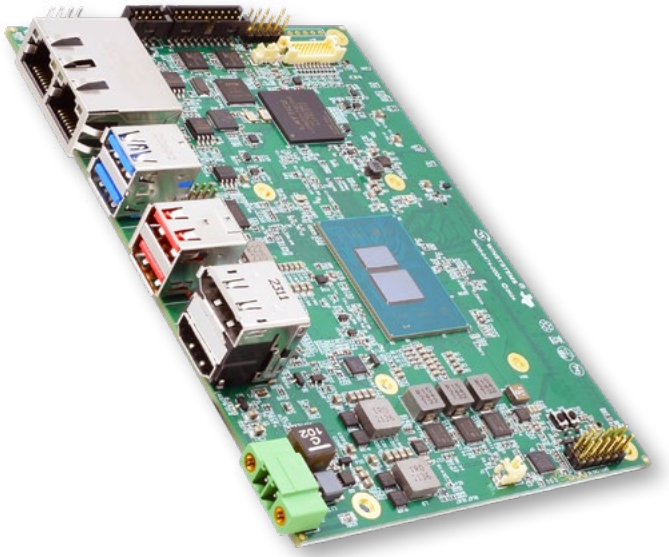
SBC-474

Fanless Rugged Single Board Computer
with Intel® Amston Lake Processors



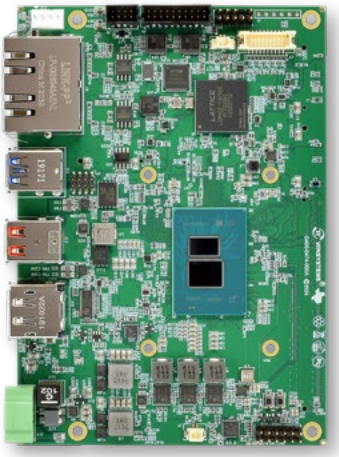
SBC-474 Single Board Computer

COMING Q1 2026!

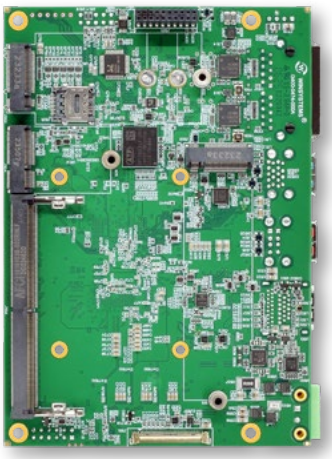
Features

- Powerful yet power-efficient industrial performance
- Amston Lake - Intel Atom® Processors x7000RE Series
- Integrated GPU and AI support features
- Triple display support with integrated UHD graphics
- Supports Wi-Fi®, Bluetooth® and cellular
- 3x M.2 expansion connectors to support PCIe, SATA, USB and I2C
- -40°C to + 85°C extended temperature range
- Extended product life cycle of 10+ years

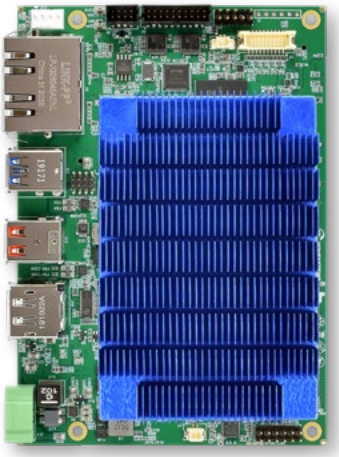
MADE IN USA



SBC Top View



SBC Bottom View



SBC Top View with Heat Sink

Product Description

WINSYSTEMS' SBC-474 is a rugged 3.5-inch single board computer (SBC) powered by an Intel Atom® X7000RE Series Amston Lake processor with integrated 16UE GPU. The SBC-474 is engineered to power robust performance for latency-sensitive applications in embedded, industrial IoT, and communications markets with exceptional reliability.

Designed for flexibility to meet the needs of your specific application, the SBC-474 features an M.2 E-Key slot and two B-Key slots that support a wide variety of I/O expansion modules with PCIe, SATA, USB3/2, Wi-Fi/Bluetooth, cellular connectivity and more. It is built to perform in harsh industrial environments and operates from -40°C to +85°C.

With support for Windows 11, Ubuntu Linux, and other x86-compatible real-time operating systems, developers can build and deploy in their preferred environment. It supports integrated AI datatype support on the CPU and a custom configurable UEFI based BIOS, to deliver power-efficient accelerated performance for real-time control and secure edge computing.

SBC-474

Technical Specifications

PART NUMBER	**SBC-474**		
PROCESSOR	Amston Lake, the Intel Atom® Processor x7000RE Series with industrial integrated GPU		
	Intel Atom® x7211RE Cores: 2 Speed: 1.0 (3.2) GHz Cache: 6 MB of L3 TDP: 6 W	Intel Atom® x7433RE Cores: 4 Speed: 1.5 (3.4) GHz Cache: 6 MB of L3 TDP: 9 W	Intel Atom® x7835RE Cores: 8 Speed: 1.3 (3.6) GHz Cache: 6 MB of L3 TDP: 12 W
OPERATING SYSTEM	Windows 11 IoT, Ubuntu Linux, other x86 real-time OS		
SOFTWARE	• Custom configurable UEFI based AMI BIOS • System Management Libraries and Tools		
SECURITY	On-board discrete TPM 2.0 hardware security		
RAM	8GB or 16GB DDR5 4800 MT/s, non-ECC		
STORAGE	• 128GB eMMC on-board • Optional MVNe or SATA		
DISPLAY	• Triple display support with UHD Graphics 32EU integrated graphics up to 1.2 GHz • HDMI 2.0 • DisplayPort++ • eDP VESA 40-pin		
AUDIO	HD Audio • 1x line out • 1x mic in		
NETWORK	2x 2.5 GbE (Intel i226) RJ-45		
EXPANSION	• M.2 E-Key 2230 (WiFi/Bluetooth®) • M.2 B-Key 2280 (SATA, NVMe, or I/O) • M.2 B-Key 2242/2252/2260/3042/3052/3060 (WAN/Cellular with Nano SIM or I/O)		
I/O	• 10x GPIO • 2x USB 3.0 • 7x USB 2.0 (3 used for M.2) • 2x Multi-Protocol Serial Ports (2mm HDR) • I2C • Nano SIM socket • Watchdog Timer 1-255		
POWER	• Wide Power Input: +9V to +36V • TDP: 22W* *Average power use under a standard load.		
THERMAL SOLUTIONS	1 = Heat Spreader	2 = Heatsink	
MECHANICAL	• Dimensions: 3.5", 146mm x 102mm x 35mm (5.75" x 4")		
ENVIRONMENTAL	• Industrial Temperature: -40°C to +85°C (-40ºF to +185°F) • Humidity: 5% to 95% non-condensing • RoHS Compliant		

Order Information - ASK ABOUT PRE-ORDERING

SBC PART NUMBER	**SBC-474-P-R-T** P= CPU (x7211RE, x7433RE, x7835RE) R = DDR5 4800 MT/s RAM (8GB, 16GB) T = Thermal option (1 = heat spreader, 2 = heatsink)
ACCESSORIES	Accessory details coming soon

Expansion and Configuration Options

WINSYSTEMS provides additional cables, expansion cards, power supplies, and solid state drives to complete your embedded computing solution including data acquisition, communications, location, and other features. Our engineers are available to guide you through product selection and configured options.

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